

**AMENDMENTS TO THE SPECIFICATION**

**Page 10, delete the first full paragraph [44] and insert:**

Vias 302d are formed at various locations in the substrate and provide passages between the first face and the second face. Vias 302d are present to make the electrical connection between the base conductors 307. The vias 302d are used to transport a component signal from one conducting layer to another. The vias in the substrate material 302 thereby allow conductive traces ~~403~~ 303 to pass through from one side of the substrate to the other. Ordinarily, a plurality of vias 302d are used but only a single via 302d is illustrated for convenience.

**Page 10, delete the paragraph [45] bridging pages 10 and 11 and insert:**

The vias allow conductive traces ~~403~~ 303 to pass through from one side of the substrate to the other. There is no restriction on the location of such vias in the base structure. The conductive material of the conductive layer 306 can be copper, nickel, or a gold layer for example. An adhesive layer 304, for chip attachment, is disposed on the first face 301a of the substrate 301. The adhesive 304 is disposed along the opening 301c in the substrate 301 and does not reach to the edges of the substrate 301. Thereby, a portion of the conductive layer 306 along the edges of the first face 301a of the substrate material is left free from adhesive 304. The adhesive 304 can comprise for example, electrically conductive or non-conductive epoxy, paste, or adhesive film, or the like, as would be understood by those skilled in the art, and are intended to be encompassed here.